

REMARKS

In response to the Office Action dated November 18, 2003, Applicant hereby makes the following response. Claim 9 and new claim 29 are pending. Claim 9 was rejected. With this Amendment claim 29 was added. Accordingly, claim 9 is at issue in the above-identified application.

35 U.S.C. § 103 Obviousness Rejection of Claims

Claim 9 was rejected under 35 U.S.C. § 103(a) as being unpatentable over *Tsutomu* (JP405267913A) in view of *Adkins*. Applicant respectfully traverses this rejection.

Claim 9 recites a first earthed conductor formed on a first surface of the dielectric substrate, wherein the first earthed conductor *does not cover the entire area* of the first surface, and a second earthed conductor formed on a second surface of the dielectric substrate, the second surface opposed to the first surface, wherein the first earthed conductor is connected with the second earthed conductor. None of the above cited references, either alone or in combination, teach or even suggest a circuit device, comprising a first earthed conductor connected with a second earthed conductor, wherein the first earthed conductor *does not cover the entire area* of a first surface. For example, *Adkins* teaches a waveguide structure 10 formed from a body 12 having respective opposing substantially planar faces 14, 16 and an intermediate signal path layer 18 positioned between the opposing faces. (See *Adkins*, column 4, lines 16-21). The body 12 can typically be formed from two respective dielectric layers 20, 22 that can be laminated together or secured by appropriated means. (See *Adkins*, column 4, lines 21-24). Each dielectric layer includes a respective ground layer 24, 26 positioned on one side thereof to form respective ground planes as illustrated in Figs. 1 and 3. (See *Adkins*, column 4, lines 27-30). However, *Adkins* does not teach nor suggest a first earthed conductor formed on a first surface of a

dielectric substrate, wherein the first earthed conductor does not cover *the entire area of the first surface*. While *Tsutomu* teaches a mesh ground plane, the mesh ground plane is not formed on a first surface of a dielectric substrate but rather formed *through* a dielectric layer. (See *Tsutomu*, Purpose) Furthermore, there is no suggestion or teaching within *Tsutomu* that suggests the mesh ground plane could be used or substituted for the ground planes 24, 26 for a waveguide structure 10, as taught within *Adkins*.

New claim 29 recites a circuit device, comprising a second earthed conductor formed on a second surface of a dielectric substrate, the second surface opposed to a first surface, wherein a first earthed conductor is connected with the second earthed conductor *only along the periphery of the dielectric substrate*. None of the above cited references, either alone or in combination, teach or even suggest a circuit device, comprising a first earthed conductor connected with a second earthed conductor *only along the periphery of the dielectric substrate*. For example, *Adkins* teaches forming conductive vias which extend through the dielectric layers and interconnect the ground planes 24 and 26, however these conductive vias 30, as illustrated in Fig. 2, are formed all along the structure 10, and not *along the periphery of a dielectric substrate*.


Accordingly, Applicant submits that the claimed invention is not anticipated by nor obvious over the applied references, either alone or in combination. Withdrawal of these grounds of rejections is respectfully requested.

CONCLUSION

In view of the remarks set forth above, Applicant respectfully submits that the present invention is in condition for allowance. Early notification to such effect is earnestly solicited. Should the Examiner have any remaining issue, Applicant kindly request that the Examiner contact the undersigned.

Respectfully submitted,

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